

**Average Weight: 13.9g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.76186</b>	<b>5.49</b>
	Silicon	7440-21-3	100.00		0.7618	
<b>Solder Bump</b>					<b>0.03679</b>	<b>0.27</b>
	Tin	7440-31-5	63.00		0.023176	
	Lead	7439-92-1	37.00		0.013611	
<b>Underfill</b>					<b>0.07400</b>	<b>0.54</b>
	Epoxy Resin A	9003-36-5	20.00		0.0148	
	Epoxy Resin B	25068-38-6	3.00		0.00222	
	Silica	60676-86-0	70.00		0.0518	
	Hardener	19900-65-3	7.00		0.00518	
<b>Heat Spreader</b>					<b>6.000000</b>	<b>43.27</b>
	Copper	7440-50-8	99.90		5.9940	
	Nickel	7440-02-0	0.10		0.000600	
<b>Heat Spreader Adhesive</b>					<b>0.150000</b>	<b>1.0819</b>
	Organopolysiloxane mixture		100.00		0.150000	
<b>Substrate</b>					<b>5.88000</b>	<b>42.41</b>
	Copper	7440-50-8	47.15	Metal layer	2.77242000	
	Nickel	7440-02-0	0.53	Metal layer	0.03116400	
	Gold	7440-57-5	0.12	Metal layer	0.00706500	
	Halogen fire retardant		5.25		0.3087000	
	Glass fiber	N/A	10.30		0.6056400	
	BT (core)	N/A	28.00		1.6464000	
	Solder mask	N/A	8.65		0.50862000	
<b>Solder Balls</b>					<b>0.96234</b>	<b>6.94</b>
	Tin	7440-31-5	95.50		0.9190347	
	Silver	7440-22-4	4.00		0.0384936	
	Copper	7440-50-8	0.50		0.0048117	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/14/06	1.0	Initial Xilinx release.
6/29/06	1.1	100% Material Declaration.
9/27/06	1.2	Updated component descriptions.
7/20/10	1.3	Updated Heat Spreader substance description.

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